

In the Claims

Claims 1-11 (Canceled).

12 (Original). A method of forming a multi-chip module comprising:

adhesively securing a first chip to a first surface of a laminate layer;
inverting the assembly of said laminate layer and said first chip;
wire bonding said first chip to a second surface of said laminate layer;
securing a second chip to the second surface of said laminate layer using bumps;
positioning said first and second chips on said laminate layer so that at least a portion of said laminate layer extends outwardly beyond said first and second chips; and
providing solder ball contacts on said first surface of said extension electrically coupled to said first and second chips.

13 (Original). The method of claim 12 including aligning said first and second chips over one another.

14 (Original). The method of claim 13 including providing a pair of extensions extending outwardly beyond said first and second chips.

15 (Original). The method of claim 13 including aligning said chips so as to form an extension of said laminate layer that extends outwardly beyond said chips and completely around said module.

16 (Original). The method of claim 14 including providing solder balls on said contacts on said extensions.

17 (Original). The method of claim 12 including filling a region between said chips with an encapsulant.

18 (Original). The method of claim 17 including forming a passage through said laminate layer and forming wire bonds from said first chip through said passage to the second surface of said laminate layer.

19 (Original). The method of claim 17 including coupling said contact and said first and second chips through traces extending through said laminate layer.

Claims 20-29 (Canceled).

30 (Original). A method comprising:

coupling a first chip to a first side of a support structure;
coupling a second chip to a second side of said support structure;
causing said support structure to extend outwardly beyond the first chip; and
providing solder ball pads on the portion of said structure extending outwardly beyond said first chip, said pads electrically coupled to said first and second chips.

31 (Original). The method of claim 30 wherein coupling a first chip includes adhesively coupling a first chip to said support structure.

32 (Original). The method of claim 31 wherein coupling a first chip includes wire bonding said first chip to bonding pads on said second side of said support structure.

33 (Original). The method of claim 30 wherein coupling a second chip includes bump bonding said second chip to said second side of said support structure.

34 (Original). The method of claim 30 wherein causing said support structure to extend outwardly includes causing said support structure to extend outwardly from two opposed edges of the first chip.

35 (Original). The method of claim 34 wherein causing said support structure to extend outwardly includes causing said support structure to extend outwardly beyond four edges of said first chip.

36 (Original). The method of claim 30 wherein causing said support structure to extend outwardly includes causing said support structure to extend outwardly beyond said first and second chips.

37 (Original). The method of claim 30 including coupling said first and second chips to said solder ball pads on said portion via traces extending through said structure.